

## EPE6059GM & EPE6059GM-RC



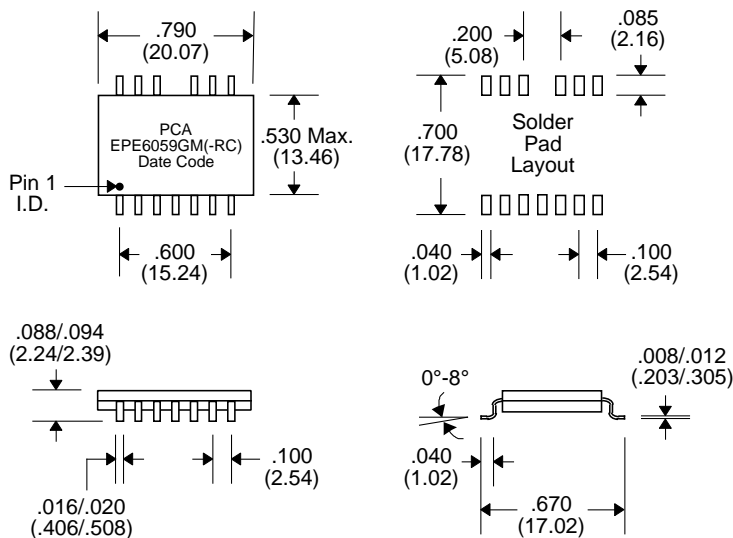
- Optimized for AMD/PHY type chip for Card Bus
- Robust construction allows for IR/VP processes
- Complies with or exceeds IEEE 802.3, 10Base-T Standards
- Hipot : 200 Vrms (for 1 minute between channels)
- Add "-RC" after part number for RoHS Compliant
- Storage Temperature : -40°C to +125°C
- Operating Temperature : 0°C to +70°C

### Electrical Parameters @ 25° C

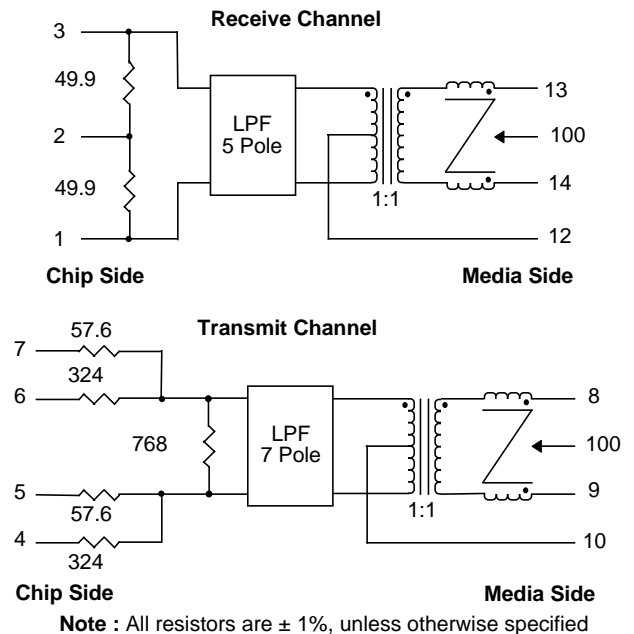
Cut-Off Frequency (MHz)	Insertion Loss (dB Max.)	Return Loss (dB Min.)	Attenuation (dB Min.)				Common Mode Rejection (dB Min.)	Crosstalk (dB Min.)
			@ 20 MHz	@ 25 MHz	@ 30 MHz	@ 40 MHz		
± 1 MHz	1-10 MHz	5-10 MHz	@ 20 MHz	@ 25 MHz	@ 30 MHz	@ 40 MHz	30-100 MHz	1-10 MHz
Xmit/Rcv	Xmit/Rcv	Xmit/Rcv	Xmit/Rcv	Xmit/Rcv	Xmit/Rcv	Xmit/Rcv	Xmit/Rcv	Between Channels
17/17	-1/-1	-15/-15	-7/-5	-18/-11	-30/-18	-35/-26	-30/-30	-30/-30

- **Isolation** : meets or exceeds 802.3 IEEE Requirements
- **Characteristic Filter Impedance** : 100
- Referenced to the filter output @ 5 MHz for filter only, excluding resistor network

### Package



### Schematic



Notes :	EPE6059GM	EPE6059GM-RC
1. Lead Finish	SnPb	Hot Tin Dip (Sn) †
2. Peak Temperature Rating	225°C	250°C
3. Moisture Sensitive Levels	MSL = 3 (168 Hours, 30°C/60%RH)	MSL = 4 (72 Hours, 30°C/60%RH)
4. Weight	TBD grams	TBD grams
5. Packaging Information	(Tube)	23 pieces/tube
	(Tape & Reel)	600 pieces/13" reel
		600 pieces/13" reel

† Lead Material : Ni Barrier over Cu

Unless Otherwise Specified Dimensions are in Inches /mm ± .010 / .25